

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT																		
NATURE OF CONVEYANCE:	ASSIGNMENT																		
CONVEYING PARTY DATA																			
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>I-CHANG SHIH</td> <td>09/30/2013</td> </tr> <tr> <td>YI-JIE CHEN</td> <td>09/30/2013</td> </tr> <tr> <td>CHIA-CHENG CHANG</td> <td>09/30/2013</td> </tr> <tr> <td>FENG-YUAN CHIU</td> <td>09/30/2013</td> </tr> <tr> <td>YING-CHOU CHENG</td> <td>10/01/2013</td> </tr> <tr> <td>CHIU HSIU CHEN</td> <td>09/30/2013</td> </tr> <tr> <td>BING-SYUN YEH</td> <td>09/30/2013</td> </tr> <tr> <td>RU-GUN LIU</td> <td>09/30/2013</td> </tr> </tbody> </table>		Name	Execution Date	I-CHANG SHIH	09/30/2013	YI-JIE CHEN	09/30/2013	CHIA-CHENG CHANG	09/30/2013	FENG-YUAN CHIU	09/30/2013	YING-CHOU CHENG	10/01/2013	CHIU HSIU CHEN	09/30/2013	BING-SYUN YEH	09/30/2013	RU-GUN LIU	09/30/2013
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RU-GUN LIU	09/30/2013																		
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PROPERTY NUMBERS Total: 1																			
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14045138</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14045138														
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Application Number:	14045138																		
CORRESPONDENCE DATA																			
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NAME OF SUBMITTER:

DAVID W. POTASHNIK

Signature:

/David W. Potashnik/

Date:

10/03/2013

Total Attachments: 10

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Docket No.TSMCP339US

Filing Date:

PATENT ASSIGNMENT

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AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

"3D IMAGE PROFILING TECHNIQUES FOR LITHOGRAPHY" for which:

a non-provisional application for United States Letters Patent:

was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney); or

was filed on _____ and accorded U.S. Serial No. _____; or

will be filed without this executed PATENT ASSIGNMENT. ASSIGNOR hereby authorizes and requests ASSIGNEE'S legal representatives, the attorneys associated with Customer No. _____, to insert below in this document this APPLICATION's U.S. Serial Number and filing date, when known:

U.S. Serial No. _____

filed on _____

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to

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Filing Date:

any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2013.09.30
Date

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TSMC Docket No. TSMC2013-0700

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